

ABSTRACT OF THE DISCLOSURE

04/490502

5 A substrate is plotted into a plurality of blocks,
and each block is plotted into one or a plurality of
device-forming regions. By using a first manufacturing
line, a conductive film, an insulating film and a
semiconductor film which constitute TFT are formed in
the device-forming region. Then, primary cutting is
performed to cut the substrate into the respective
blocks and form a plurality of sub-TFT substrates. Then,
10 by using a second manufacturing line, processing is
performed for each sub-TFT substrate in accordance with
specifications of a liquid crystal panel to be
manufactured. Then, secondary cutting is performed to
cut the sub-TFT substrate into respective device-forming
15 regions.

005210-20506460